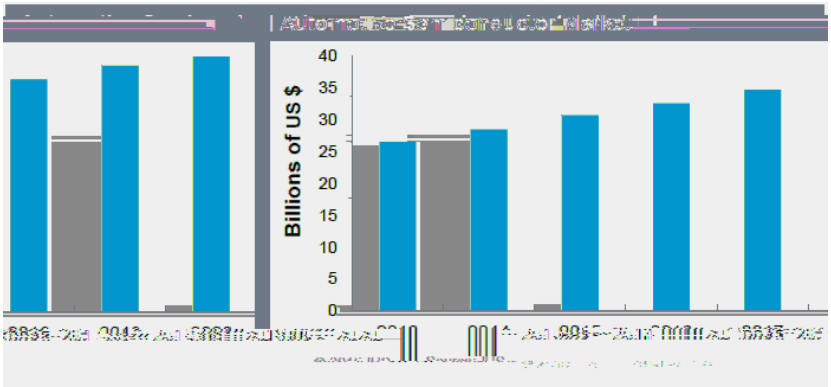
$GYDQFHG 3DFNDJLQJ IRU $XWRPRWLYH 'DVKE

$EVWUDFW

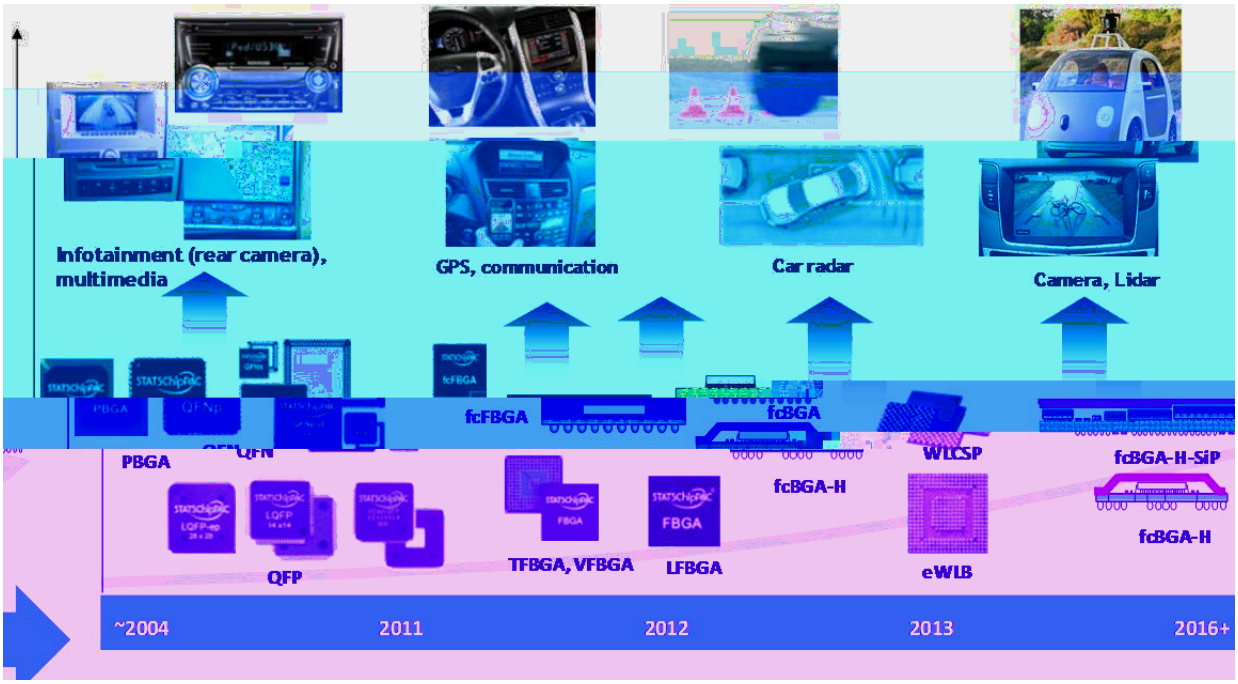
.H\ZRUGV

,QWURGXFWLRQ



$XWRPRWLYH 5HTXLUHPHQWV

$XWRPRWLYH ,& 3DFNDJLQJ 7UHQGV



3DFNDJH DQG %RDUG /HYHO 4XDOLILFDWLRQ 'DWD

eWLB size (mm2)	'LHVL PP	]H3LWFK PP	*Die No. / RDL No.*	, 2	$(& 4XDOLILFDWLRQ 5HOLDELOLW\ 7HVW

Test		Condition		Status
Package Level	MSL1	MSL1, 260C Reflow (3x)	-	Pass
	Temperature Cycling (TC) after Precon**	-55 C to 125C	1000x	Pass
	HAST (w/o bias) after Precon	130C / 85% RH	96hrs	Pass
	High Temperature Storage (HTS)	150C	1000h	Pass
	HAST with Bias after Precon	130C / RH 85%	168hrs	Pass
	Temperature Humidity Bias (performed mounted on PCB)***	85C/85%RH	1000 hrs	Pass

• **Results based on Package eTest : <u>** Customer qualified TC C -65/150C 1000x</u>**

Board Level Reliability				
Board Level	Temperature cycling on board (TCoB)	-40C to 125C, 1cy/hr	500x	Pass
	Drop Test	JEDEC		Pass

5HIHUHQFHV